

Electronic Patent Application Fee Transmittal

Application Number:	10700782			
Filing Date:	03-Nov-2003			
Title of Invention:	Bath and method for high rate copper deposition			
First Named Inventor/Applicant Name:	Bioh Kim			
Filer:	Jeffrey M. Sakoi/Shannon Hill			
Attorney Docket Number:	SEMT119849			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 2 months with \$0 paid	1252	1	460	460

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				460